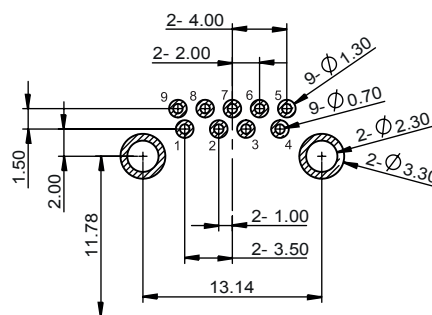
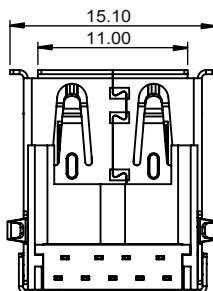
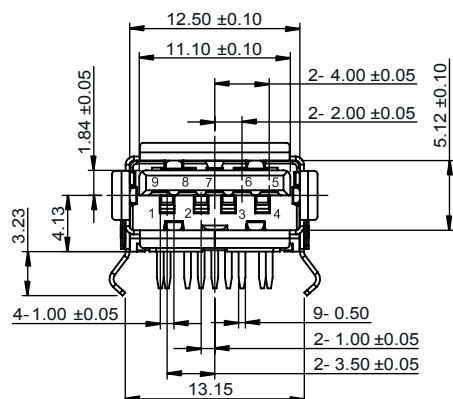
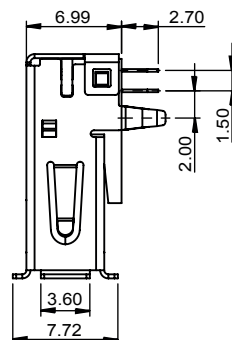
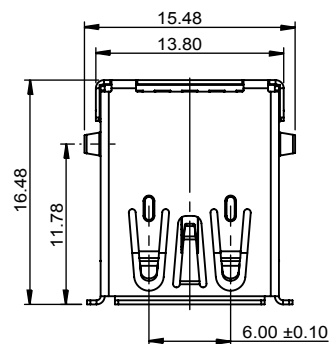




CONNECTOR FRONT EDGE

PCB LAYOUT * - COMPONENT VIEW

TECHNICAL CHARACTERISTICS

MATERIAL

INSULATOR: LCP
FLAMABILITY RATING: UL94-V0
COLOR: BLUE
CONTACT MATERIAL: PHOSPHORE BRONZE
CONTACT TYPE: STAMPED
CONTACT PLATING: UNDERPLATE Nickel
CONTACT AREA Pd-Ni + Gold
SOLDER TAIL AREA Matt Tin
SHIELDING: BRASS MATT TIN PLATED

ENVIRONMENTAL

OPERATING TEMPERATURE: -20 up to +85°C
COMPLIANCE: RoHS & LEAD FREE AS PER DIRECTIVE 2002/95/EC
HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21

ELECTRICAL

CURRENT RATING:
- PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A Max
- OTHER PINS 0.25 A Max
WORKING VOLTAGE: 30Vac
DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min
INSULATION RESISTANCE: > 100MΩ
CONTACT RESISTANCE:
- PIN 1 & PIN 4: 30mΩ Max
- OTHER PINS: 50mΩ Max
IMPEDANCE: 90Ω +/- 15Ω @ 50ps RISE TIME (20~80%)

STANDARD

CERTIFIED: E323964 / MODEL NUMBER 692121030100

MECHANICAL

INSERTION FORCE: 35.0N Max
EXTRACTION FORCE: 10.0N min
QUALITY CLASS: 5000 MATING CYCLES

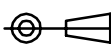
SOLDERING

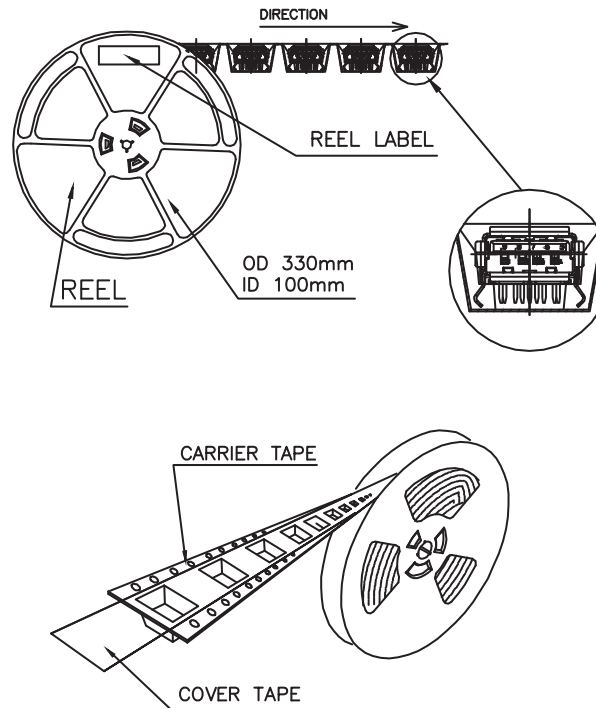
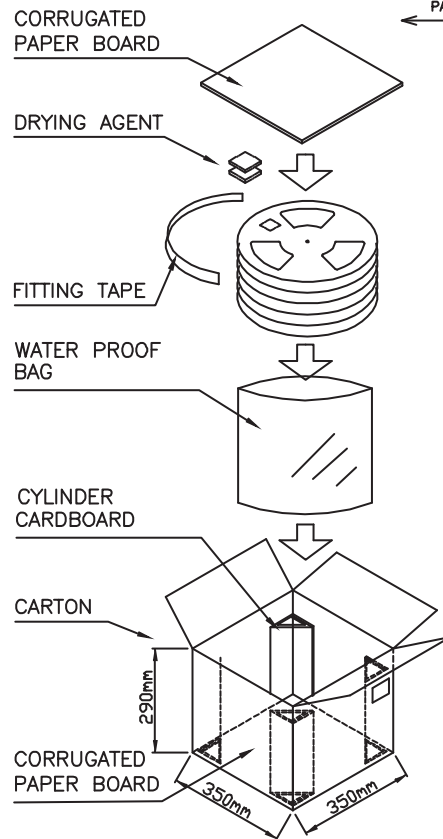
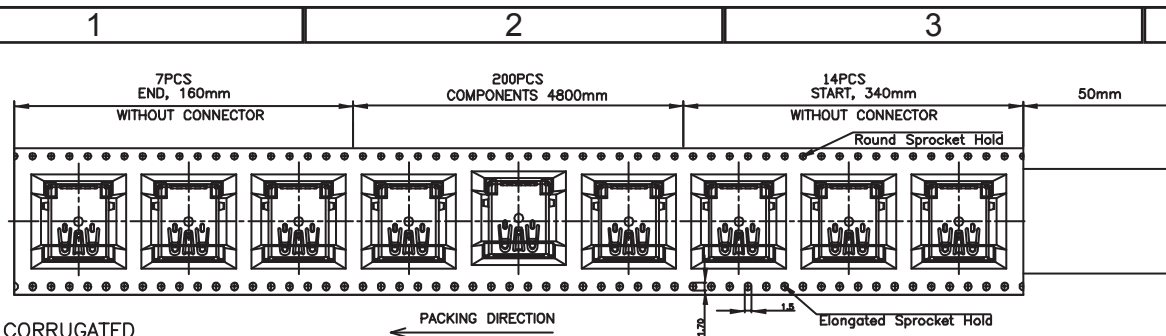
WAVE & REFLOW PROCESS AS PER JEDEC J-STD-020D

PACKAGING

TAPE & REEL

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

RoHS Compliant				* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.				
G				PROJECTION: 	GENERAL TOLERANCE .X = $\pm$ 0.2 .XX = $\pm$ 0.15	 WÜRTH ELEKTRONIK		
F								
E	09-NOV-11	STENCIL	GG					
D	27-OCT-11	MODIFICATION	GG					
C	21-SEP-11	NOTE	GG	APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A		SIZE A4
B	10-MAY-11	UL	GG		SCALE:			
A	04-AUG-10	PDF	JP		SHEET: 1/3	WERI PART NO: 692 121 030 100		
REV	DATE	FILE	BY		DRAW: JOE			



NOTES

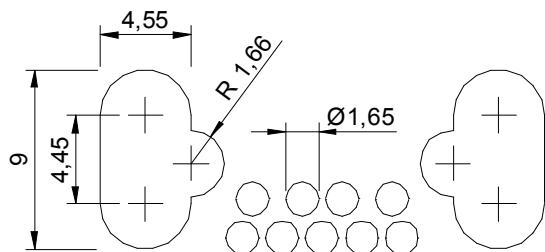
1. MATERIALS: PS
2. 1000PCS/CARTON
3. RoHS
All Material in According With The RoHS Environment Related Substances List Controlled.
4. PART NO.

Packing SPEC

1. Fill in a corrugated paper board
2. Put 5 reels of products into water proof bag, with 2pcs of drying agent.
3. Make all reel label side up.
4. The upper formation puts corrugated
5. As the indication sticking the label at the certain place of carton.

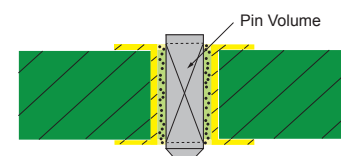
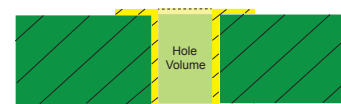
RoHS Compliant				PROJECTION: 	GENERAL TOLERANCE .X = ± 0.2 .XX = ± 0.15	 WÜRTH ELEKTRONIK	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A WERI PART NO: 692 121 030 100	SIZE A4
G								
F								
E								
D								
C				APPROVAL: RJ	UNIT: MM			
B					SCALE:			
A					SHEET: 2/3			
REV	DATE	FILE	BY		DRAW: JOE			

Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT * - COMPONENT VIEW

PCB cross section

 Free volume for solder paste

Theoretical Formula for Through Hole pins

Volume of the stencil aperture = (Hole volume - Pin volume) x 2
or

$$\text{Volume of solder paste} = (\text{Hole volume} - \text{Pin volume}) \times 2$$

Stencil

Stencil Thickness: 150 μm

PCB

PCB thickness: 1.6mm

RoHS Compliant		* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS					
G				PROJECTION: 	GENERAL TOLERANCE $.X = +/_{.0.2}$ $.XX = +/_{.0.15}$		
F							
E							
D							
C				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 HORIZONTAL TYPE A	SIZE A4
B					SCALE:		
A					SHEET: 3/3	WERI PART NO: 692 121 030 100	
REV	DATE	FILE	BY		DRAW: JOE		